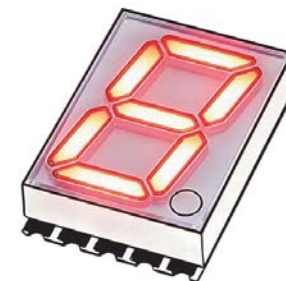
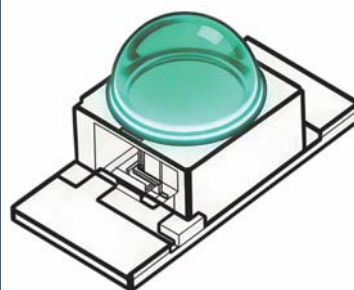


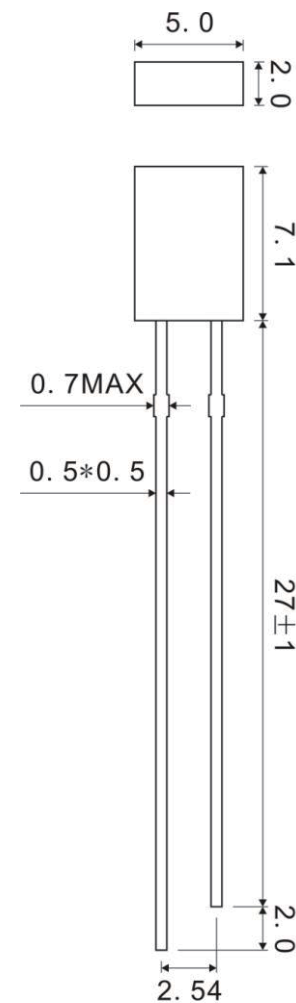
DIP LEDs



Features/产品描述

- 胶体尺寸
Package : 2x5mm
- 颜色:高亮红光
Color:Ultra Bright Standard Red
- 胶体:红色胶体
Lens:Red Diffused Mold
- 规范标准包装
STD Package
- 环保产品, 符合RoHS要求
Meet RoHS,Green Product
- 多功能安装在P. C板或面板上
Versatile mounting on P.C board or panel

Package Outline /外形尺寸



注/ Notes: 1. 单位 : 毫米 (mm) / All dimensions are in millimeters

2. 公差: 如无特别标注则为 ± 0.2 mm / Tolerance is ± 0.20 mm unless otherwise noted

Absolute Maximum Ratings/最大绝对额定值(Ta=25°C)

参 数 Parameter	符号 Symbol	最大额定值 Rating	单 位 Unit
消耗功率 Power Dissipation	Pd	90	mW
最大脉冲电流 Peak Forward Current (1/10 占空比, 0.1ms 脉宽)	IFP	50	mA
正向直流工作电流 DC Forward Current	IF	25	mA
反向电压 Reverse Voltage	VR	5	V
工作环境温度 Operating Temperature Range	Topr	-30°C ~ +85°C	
存储环境温度 Storage Temperature Range	Tstg	-35°C ~ +85°C	
焊接条件 Soldering Condition	Tsol	波峰焊/ Wave soldering : 260°C , 5s 手动焊/Hand soldering : 300°C , 3s	

Electrical Optical Characteristics/光电参数(Ta=25°C)

参 数 Parameter	符号 Symbol	最小值 Min	代表值 Typ	最大值 Max	单 位 Unit	测试条件 Test Condition
光强 Luminous Intensity	I _v	40	70	---	mcd	IF = 20mA
半光强视角 Viewing Angle	2θ _{1/2}	---	100	---	deg	IF = 20mA
主波长 Dominant Wavelength	λ _d	---	630	645	nm	IF = 20mA
峰值波长 Peak Wavelength	λ _p	---	635	---	nm	IF = 20mA
半波宽 Spectral Line Half-Width	Δλ	---	20	---	nm	IF = 20mA
正向电压 Forward Voltage	V _F	1.8	---	2.4	V	IF = 20mA
反向电流 Reverse Current	I _R	---	---	10	μA	VR = 5V

Label Explanation/标签标识

Packaging Specifications/包装规格

CAT: 光强

Luminous Intensity Rank (单位 (mcd))

HUE: 波长

CIE 1931 Coordinate Rank (单位 (nm))

REF: 电压

Forward Voltage Rank (单位 (V))



- Notes:
1. 尺寸单位为毫米(mm)/ All dimensions are in millimeters.
 2. 无特别说明尺寸公差是 $\pm 0.2\text{mm}$ / Tolerance is $\pm 0.2\text{ mm}$ unless otherwise noted.

Reliability Testing/信赖度测试标准

测试项目 Test Item	测试条件 Test Condition	测试时间 Test Times	参考标准 Reference Standard	数量 Quantity	判定数 AC /RE
工作寿命 Operation Life	室温条件下以额定电流持续点亮; Ta= Under Room Temperature As Per Data Sheet Rating	1000 HRS	JESD22-A108	22pcs	0/1
高温储存 High Temperature Storage	环境温度Ta= 85℃±5℃	1000 HRS	JESD22-A103	22pcs	0/1
低温储存 Low Temperature Storage	环境温度 Ta= -35℃±5℃	1000 HRS	JESD22-A119	22pcs	0/1
温度循环 Temperature Cycling	85℃ ~ 25℃ ~ -35℃ ~ 25℃ 30mins 5mins 30mins 5mins	100 次循环/ 100Cycles	JESD22-A104	22pcs	0/1
冷热冲击 Thermal Shock	100 °C ~ -10°C 5mins 5mins	100 次循环/ 100Cycles	JESD22-A106	22pcs	0/1
可焊性实验 Solderability	温度最高 260℃时间: 最大 5 秒 Peak temperature range 260°C 5s max	----	JESD22-B102	22pcs	0/1

失效判定标准/Criteria For Judging Damage

项目 Test items	符号 Symbol	测试条件 Test Condition	判定标准 Criteria For Judgment	
			最大 Max	
正向电压Forward Voltage	VF	IF=20mA		U. S. L) x1.1
漏电流Reverse Current	IR	VR=5V		30μA
光强度Luminous Intensity	Iv	IF=20mA	L. S. L) x0.7	

U. S. L:Upper standard level 规格上限
L. S. L:Lower standard level 规格下限

备注/ Note:
信赖性测试基于现有的测试平台
The Reliability tests are based on existing test platform.

Soldering Specification/建议焊接温度曲线

焊接 / Soldering

1. 波峰焊焊接次数不得超过一次。

Wave soldering should not be done more than 1 times.

2. 只建议在修理和重工的情况下使用手工焊接；最高焊接温度不应超过 300 度，且须在 3 秒内完成。烙铁最大功率应不超过 30W。

Manual soldering is only suggested on repair and rework. The maximum soldering temperature should not exceed 300°C within 3 sec. And the maximum capacity of soldering iron is 30W in power.

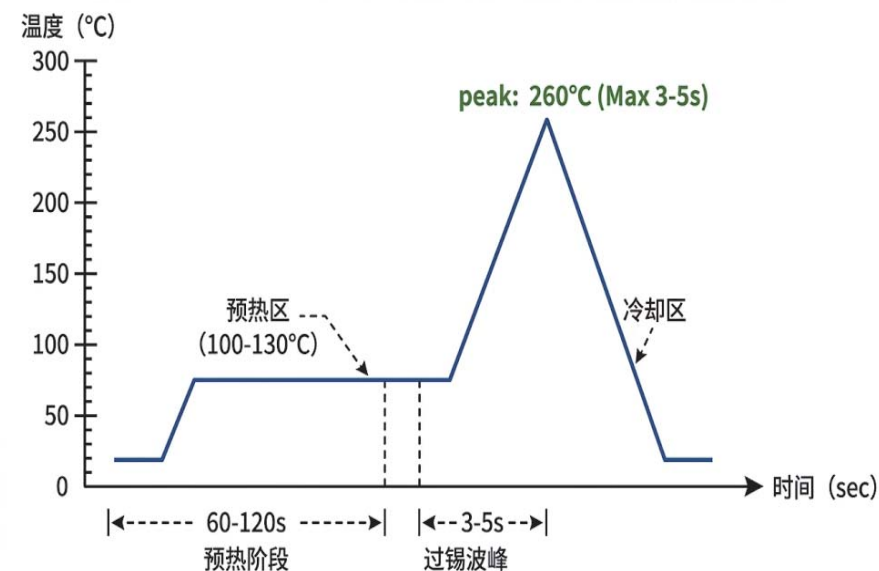
3. 焊接过程中, 严禁在高温情况下碰触胶体。

During the soldering process, do not touch the lens at high temperature.

4. 焊接后，禁止对胶体施加外力，禁止弯折 PCB，避免元件受到撞击。

After soldering, any mechanical force on the lens or any excessive vibration shall not be accepted to apply, also the circuit board shall not be bent as well.

无铅焊接/ For Lead Free Solder



Cautions/注意事项

使用/ Application

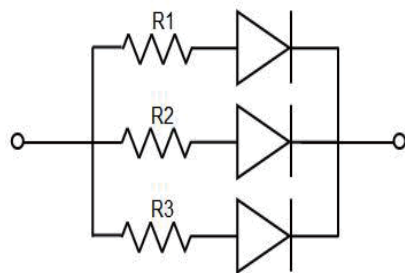
1. LED 是电流驱动元件, 电压的细微变化会产生较大的电流波动, 导致元件遭到破坏。客户应使用电阻串联作限流保护。

A LED is a current-operated device. The slight shift of voltage will cause big change of current, which will damage LEDs. Customer should use resistors in series for the Over-Current-Proof

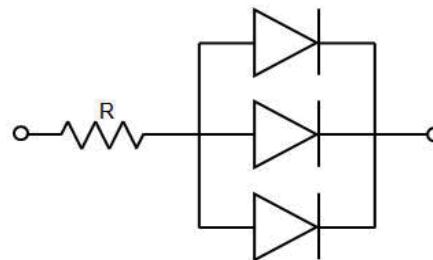
2. 为了确保多颗 LED 并联使用时光色一致, 建议每条支路使用单独电阻, 如下图模式 A 所示;

如采用下图模式 B 所示电路, LED 光色可能因每一颗 LED 不同的伏安特性而造成光色差异。

In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended to use individual resistor separately, as shown in Circuit A below. The brightness of each LED shown in Circuit B might appear difference due to the differences in the I-V characteristics of those LEDs.



电路模式/ Circuit model A



电路模式/ Circuit model B

3. 过高的环境温度会影响 LED 的亮度以及其他性能, 所以为能使 LED 有较好的性能表现应远离热源

High temperature may reduce LEDs' intensity and other performances, so keeping it away from heat source to get good performance is necessary.

存储/ Storage

1. 未打开原始包装的情况下，建议储存的环境为：温度：5℃~30℃；湿度：85%RH 以下。当库存超过两个月，使用前应做除湿处理，条件 60℃/8 小时。

Before opening original package, it is recommended to store them in the following environment:

Temperature: 5℃~30℃, Humidity: 85%RH max. When the inventory over 2 months, Should be done before treatment using dehumidification, Temperature: 60℃/8 hours.

2. 打开原始包装后，建议储存环境为： 温度 5~30° C ； 湿度 60% 以下。

After opening original package, the storage ambient for the LEDs should be in 5~30°C temperature and 60% or less relative humidity

3. LED 是湿度敏感元件，为避免元件吸湿，建议打开包装后，将其储存在有干燥剂的密闭容器内，或者储存在氮气防潮柜内。

In order to avoid moisture absorption, it is recommended that the LEDs that out of the original package should be stored in a sealed container with appropriate desiccant, or in desiccators with nitrogen ambient.

4. 打开包装后，元件应该在 24 小时（1 天）使用；且贴片后应尽快做焊接。

The LEDs should be used within 24hrs (1day) after opening the package. Once been mounted, soldering should be quick.

5. 如果干燥剂失效或者元件暴露于空气中超过 24 小时（1 天），应作除湿处理。烘烤条件：60℃ ， 24 小时。

If the moisture absorbent material (silica gel) has faded away or the LEDs stored out of original package for more than 24hrs (1 day), baking treatment should be performed using the conditions: 60℃ at least 24 hours.

ESD 静电防护/ ESD (Electrostatic Discharge)-Protection

1. 接触 LED 时应佩戴防静电腕带或者防静电手套。
A conductive wrist strap or anti-electrostatic glove should be worn when handling these LEDs
2. 所有的机器设备、工制具、工作桌、料架等等，
应该做适当的接地保护（接地阻抗值 10Ω 以内）。
All devices, equipment, machinery, work tables and storage racks, etc. must be properly grounded (Grounding impedance value within 10Ω)
3. 储存或搬运 LED 应使用防静电料袋、防静电盒以及防静电周转箱，严禁使用普通塑料制品。
Use anti-static package or boxes to carry and storage LEDs. And ordinary plastic package or boxes is forbidden to use.
4. 建议在作业过程中，使用离子风扇来压制静电的产生。
Use ionizer to neutralize the static charge during handling or operating.
5. 距离 LED 元件 1 英尺距离的环境范围内静电场电压小于 100V。
All surfaces and objects within 1 ft close to LEDs measure less than 100V.

光电参数公差/ Rank Tolerance

正向电压 REF / VF : $\pm 0.05V$

亮度 CAT / IV : $\pm 10\%$

色度坐标 X / Y : ± 0.005

波长 HUE/WLD: $\pm 1nm$

清洗/ Cleaning

建议使用异丙醇等醇类溶液清洗 LED，严禁使用腐蚀性溶液清洗。

Use alcohol-based cleaning solvents such as IPA (isopropyl alcohol) to clean LEDs if necessary

引线成型/ Lead Forming

1. 在引线成型过程中，引线应在距离环氧树脂球底部至少3毫米处弯曲。（注意：在弯曲之前，必须固定引线框架且不得触碰环氧树脂，以避免元件损坏。）

During lead formation, the leads should be bent at a point at least 3mm from the base of the epoxy bulb.(Note: Must fix lead frame and do not touch epoxy before bending to avoid components broken.)

2. 引线成型应在焊接前完成。

Lead forming should be done before soldering.

3. 在引线成型过程中，应避免对元件封装施加应力。对基座的应力可能会损坏元件特性，甚至可能导致元件断裂。

Avoid stressing the components package during leads forming. The stress to the base may damage the components characteristics or it may break the components.

4. 在室温下切割元件引线框架。在高温下切割引线框架可能会导致元件失效。

Cut the components lead frames at room temperature. Cutting the lead frames at high temperatures may cause failure of the components.

5. 在将元件安装到印刷电路板（PCB）上时，PCB的孔必须与元件的引脚位置精确对齐。如果元件在引脚处受力安装，会导致环氧树脂劣化，进而使元件性能下降。

When mounting the components onto a PCB, the PCB holes must be aligned exactly with the lead position of the components. If the components are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the components.

其他/Others

1. 本规格所描述的 LED定义应用在普通的电子设备范围（例如办公设备、通讯设备等等）。如果有更为严苛的信赖度要求，特别是当元件失效或故障时可能会直接危害到生命和健康时（如航天、运输、交通、医疗器械、安全保护等等），请事先知会敝司业务人员。

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult Sales in advance for the applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health. (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

2. 高亮度 LED产品点亮时可能会对人眼造成伤害，应避免从正上方直视。

The light output from the high luminous intensity LEDs may cause injury to human eyes when viewed directly.

3. 出于持续改善的目的，产品外观和参数规格可能会在没有预先通知的情况下作改良性变化。

The appearance and specifications of the product may be modified for improvement without prior notice.